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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-10 (canceled).

Claim 11 (currently amended): ~~The integrated circuit package according to claim 40, further~~ An integrated circuit package comprising:

a first leadframe;

a second leadframe laminated to a portion of said first leadframe thereby providing a multi-layer laminated leadframe;

a semiconductor die mounted to another portion of said first leadframe;

and

a plurality of contact balls mounted on said semiconductor die.

Claim 12 (currently amended): ~~The integrated circuit package according to claim 40, further~~ An integrated circuit package comprising:

a first leadframe;

a second leadframe laminated to a portion of said first leadframe thereby providing a multi-layer laminated leadframe;

a semiconductor die having opposing first and second surfaces, the first surface of said semiconductor die being mounted to another portion of said first leadframe; and

a third leadframe laminated to at least a portion of said second surface of said semiconductor die.

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Claim 13 (currently amended): The integrated circuit package according to claim ~~40~~11, wherein said first leadframe comprises a copper strip having silver plating on one surface and said second leadframe is soldered to an opposing second surface thereof.

Claim 14 (currently amended): The integrated circuit package according to claim ~~40~~11, wherein said second leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

Claim 15 (original): The integrated circuit package according to claim 12, wherein said third leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

Claim 16 (currently amended): The integrated circuit package according to claim ~~40~~11 wherein said semiconductor die is coated with at least one of titanium, tungsten, gold, or a combination thereof for soldering.